



PMEG6050ELP-Q

60 V, 5 A low leakage current Schottky barrier rectifier

10 March 2025

Product data sheet

1. General description

Planar Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a SOD128 small and flat lead Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Extremely low leakage current
- High power capability due to clip-bonding technology
- High temperature $T_j \leq 175\text{ °C}$
- Small and flat lead SMD plastic package
- Suitable for both reflow and wave soldering
- Qualified according to AEC-Q101 and recommended for use in automotive applications

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 154\text{ °C}$	-	-	5	A
V_R	reverse voltage	$T_j = 25\text{ °C}$	-	-	60	V
V_F	forward voltage	$I_F = 5\text{ A}$; pulsed; $T_j = 25\text{ °C}$	[1]	700	780	mV
I_R	reverse current	$V_R = 60\text{ V}$; pulsed; $T_j = 25\text{ °C}$	[1]	340	1000	nA

[1] Very short pulse, in order to maintain a stable junction temperature.

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	<p>CFP5 (SOD128)</p>	<p>sym001</p>
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG6050ELP-Q	CFP5	plastic, surface mounted package; 2 terminals; 4 mm pitch; 3.8 mm x 2.6 mm x 1 mm body	SOD128

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG6050ELP-Q	GK

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ °C}$		-	60	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; square wave; $T_{sp} \leq 154\text{ °C}$		-	5	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8.3\text{ ms}$; half-sine wave; $T_{j(init)} = 25\text{ °C}$		-	70	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ °C}$	[1]	-	750	mW
			[2]	-	1.25	W
T_j	junction temperature			-	175	°C
T_{amb}	ambient temperature			-55	175	°C
T_{stg}	storage temperature			-65	175	°C

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	200	K/W
			[1] [3]	-	-	120	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	12	K/W

- [1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.
- [2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.
- [3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm².
- [4] Soldering point of cathode tab.

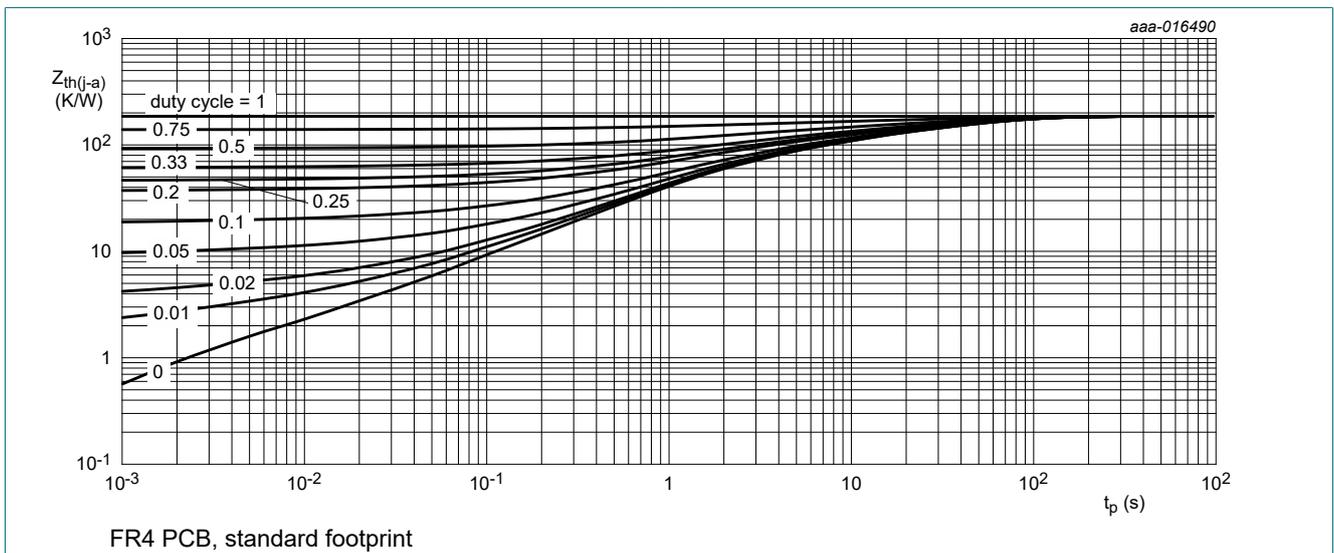


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

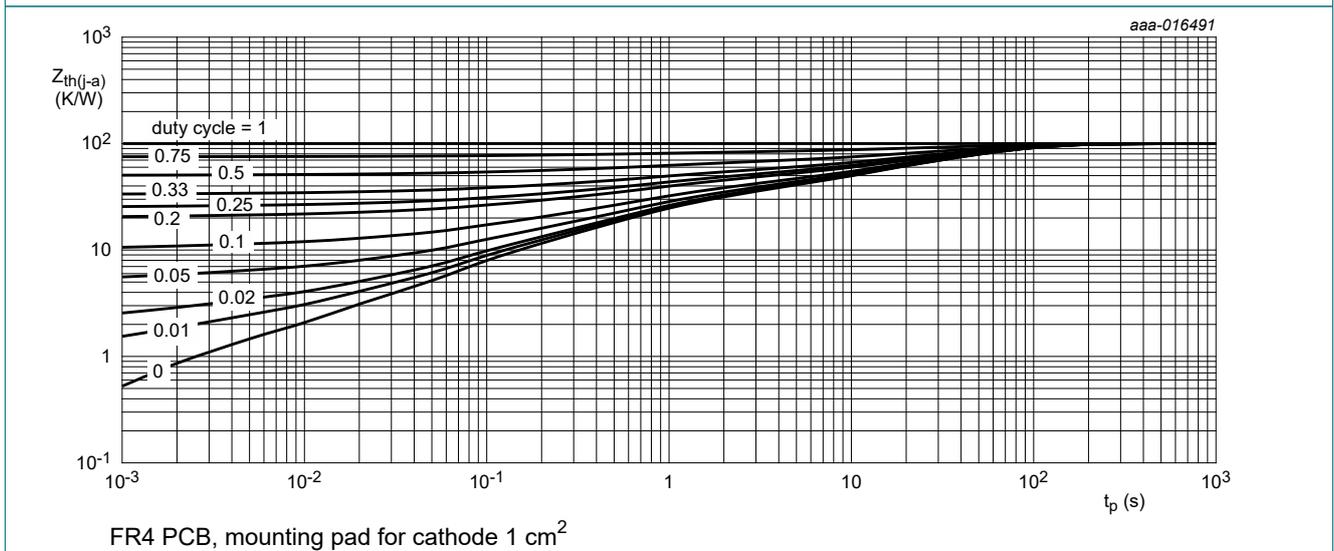


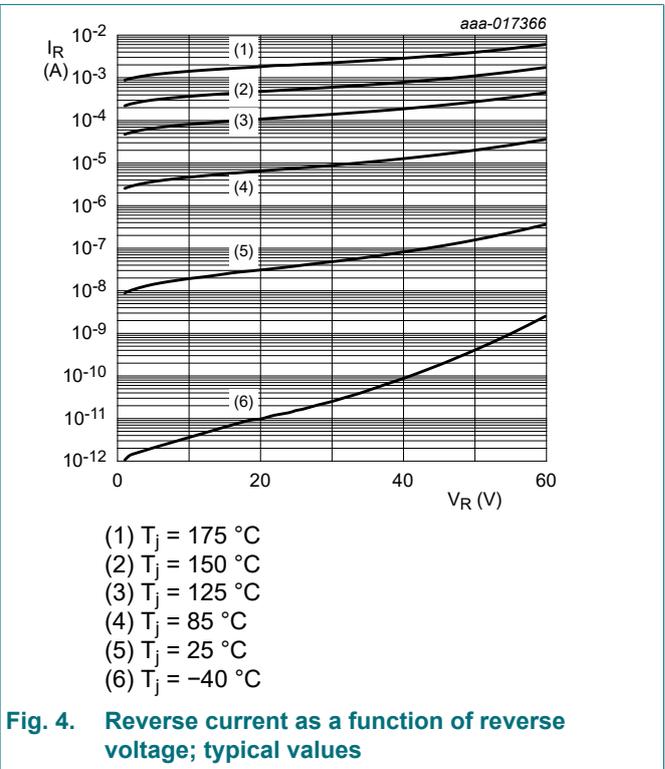
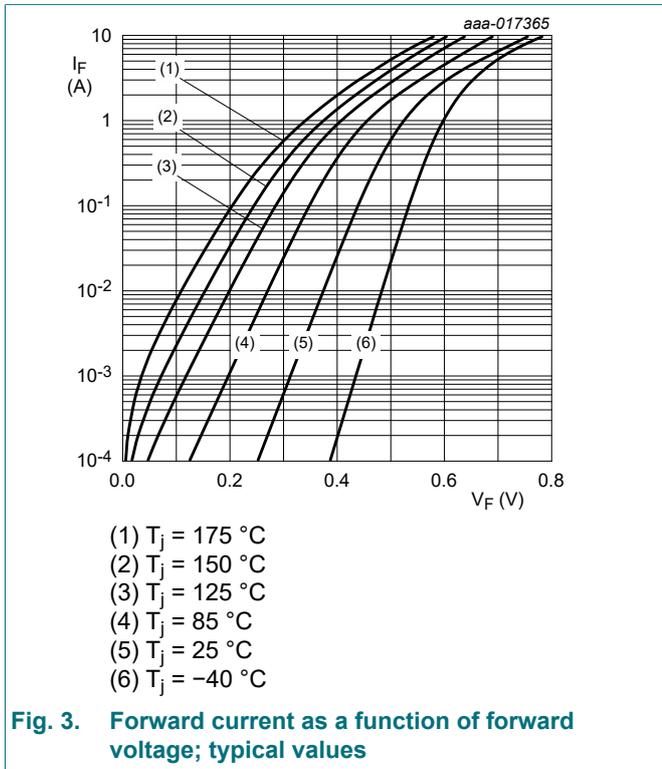
Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1 \text{ mA}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	60	-	-	V
V_F	forward voltage	$I_F = 1 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	525	585	mV
		$I_F = 5 \text{ A}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	700	780	mV
		$I_F = 5 \text{ A}$; pulsed; $T_j = -40 \text{ }^\circ\text{C}$	[1]	-	730	-	mV
		$I_F = 5 \text{ A}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	600	-	mV
I_R	reverse current	$V_R = 10 \text{ V}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	20	-	nA
		$V_R = 60 \text{ V}$; pulsed; $T_j = 25 \text{ }^\circ\text{C}$	[1]	-	340	1000	nA
		$V_R = 60 \text{ V}$; pulsed; $T_j = 125 \text{ }^\circ\text{C}$	[1]	-	440	2100	μA
C_d	diode capacitance	$V_R = 1 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	315	-	pF
		$V_R = 4 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	190	-	pF
		$V_R = 10 \text{ V}$; $f = 1 \text{ MHz}$; $T_j = 25 \text{ }^\circ\text{C}$		-	125	-	pF
t_{rr}	reverse recovery time ramp recovery	$di_F/dt = 200 \text{ A}/\mu\text{s}$; $I_F = 6 \text{ A}$; $V_R = 26 \text{ V}$; $T_j = 25 \text{ }^\circ\text{C}$		-	10	-	ns
I_{RM}	peak reverse recovery current			-	0.89	-	A
Q_{rr}	reverse recovery charge			-	5	-	nC

[1] Very short pulse, in order to maintain a stable junction temperature.



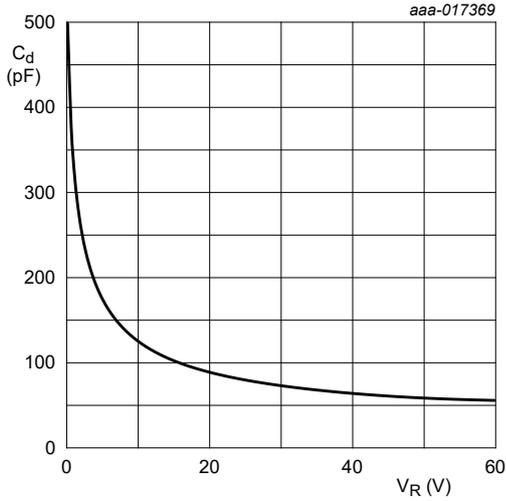


Fig. 5. Diode capacitance as a function of reverse voltage; typical values

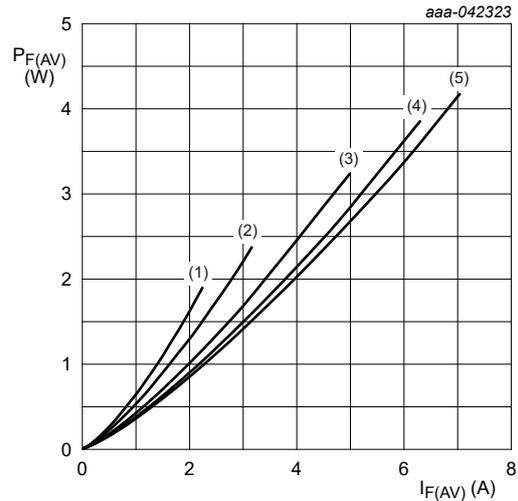


Fig. 6. Average forward power dissipation as a function of average forward current; typical values

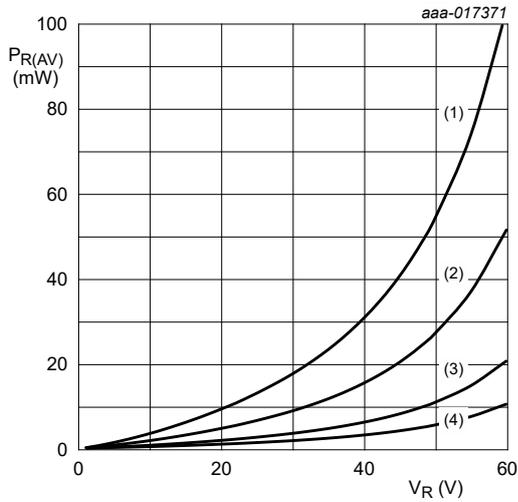


Fig. 7. Average reverse power dissipation as a function of reverse voltage; typical values

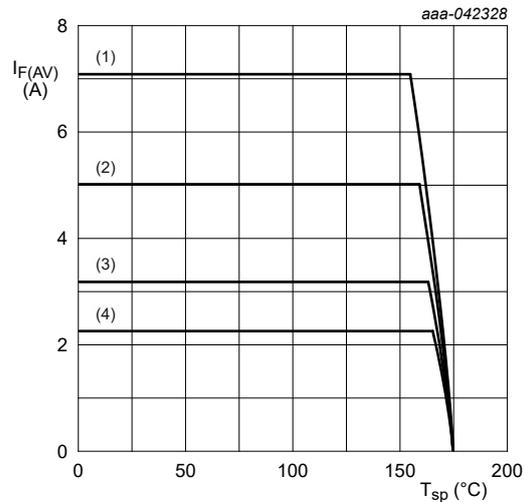


Fig. 8. Average forward current as a function of solder point temperature; typical values

11. Test information

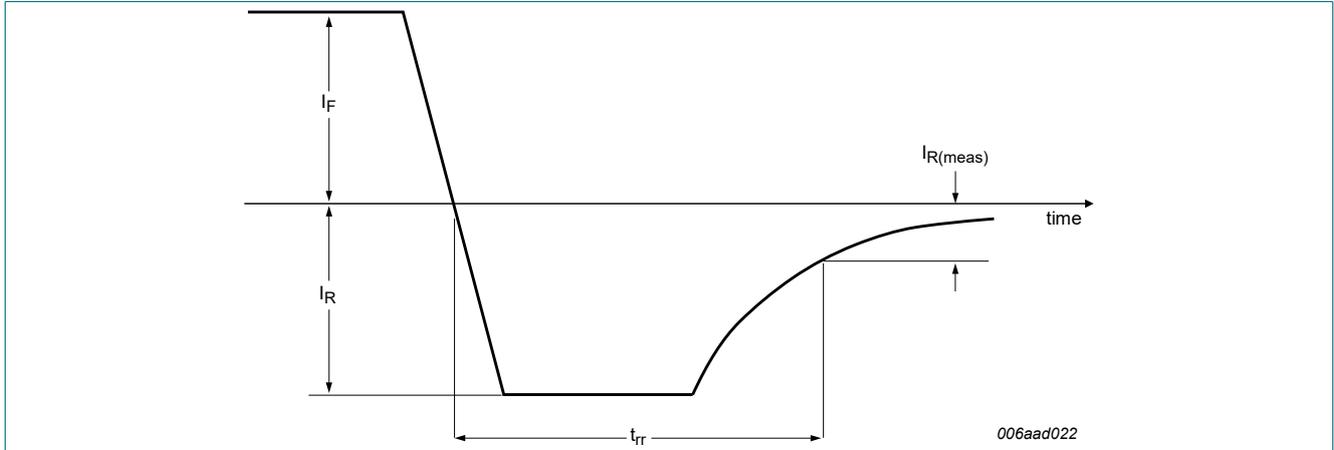


Fig. 9. Reverse recovery definition

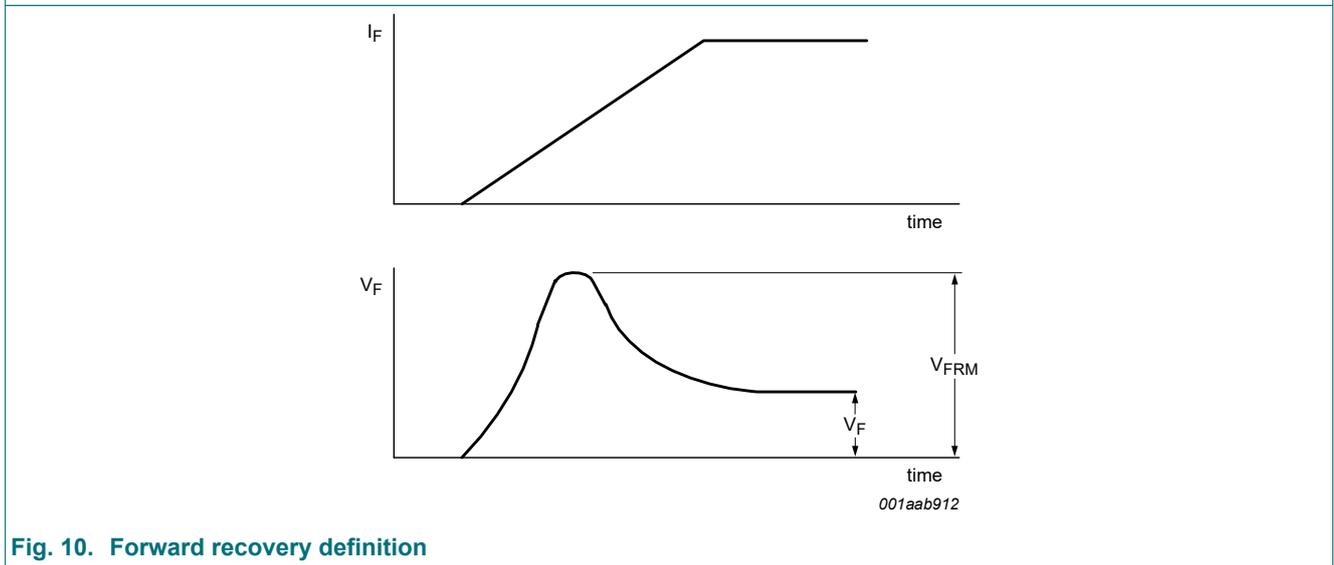


Fig. 10. Forward recovery definition

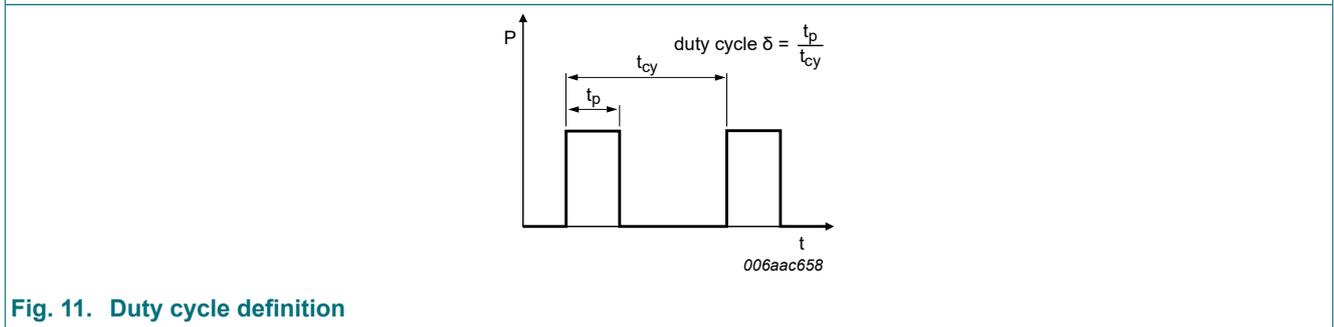


Fig. 11. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:

$$I_{F(AV)} = I_M \times \delta \text{ with } I_M \text{ defined as peak current,}$$

$$I_{RMS} = I_{F(AV)} \text{ at DC,}$$

$$I_{RMS} = I_M \times \sqrt{\delta} \text{ with } I_{RMS} \text{ defined as RMS current.}$$

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

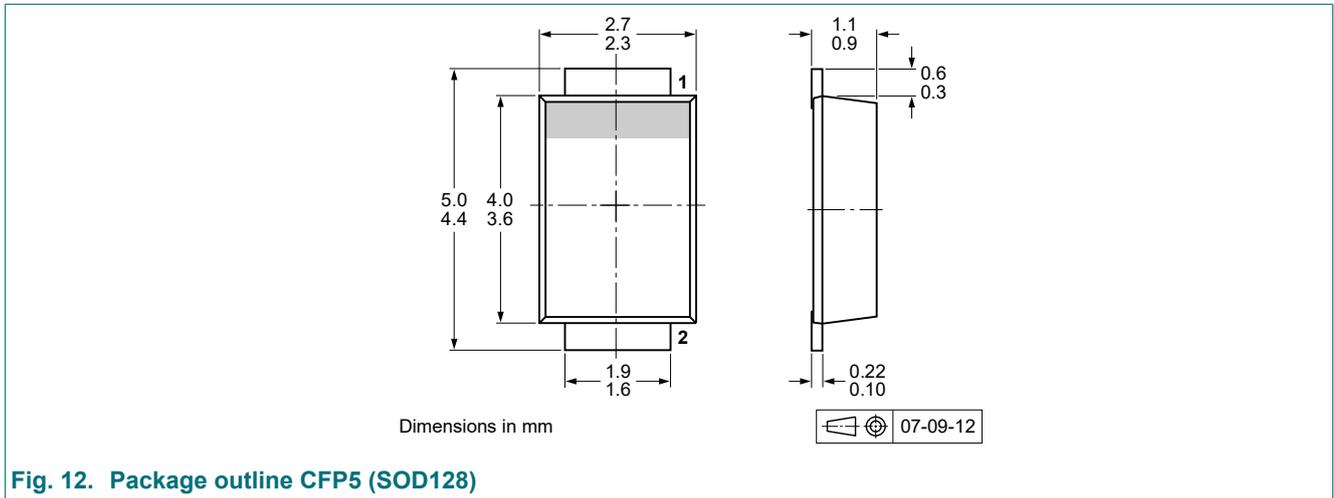


Fig. 12. Package outline CFP5 (SOD128)

13. Soldering

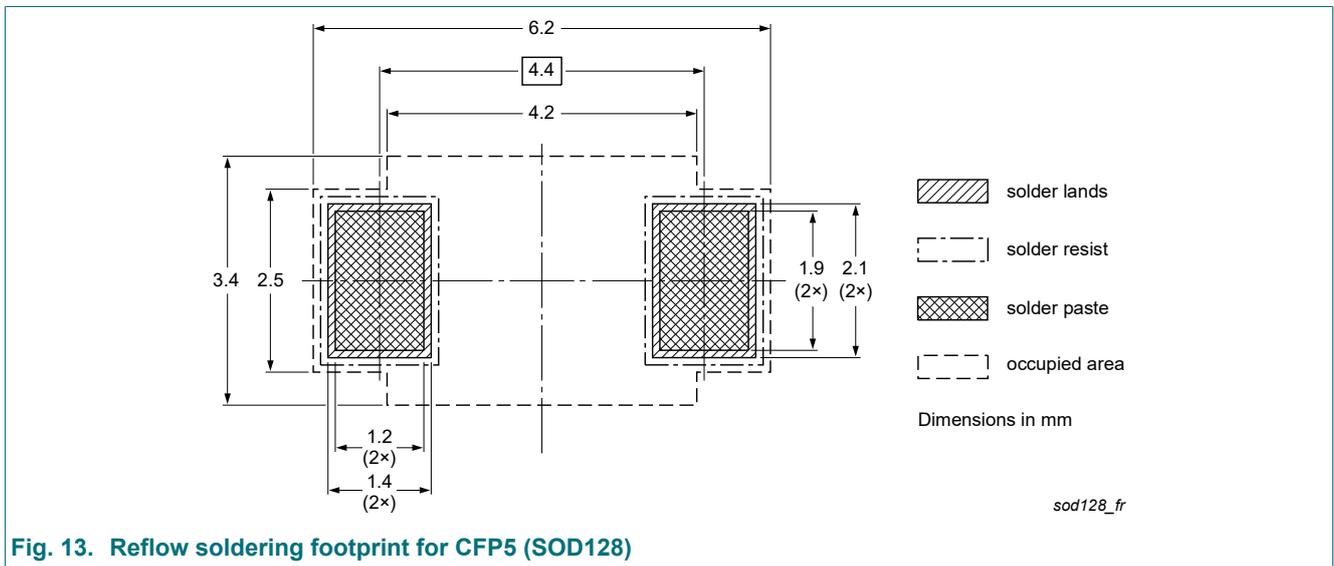


Fig. 13. Reflow soldering footprint for CFP5 (SOD128)

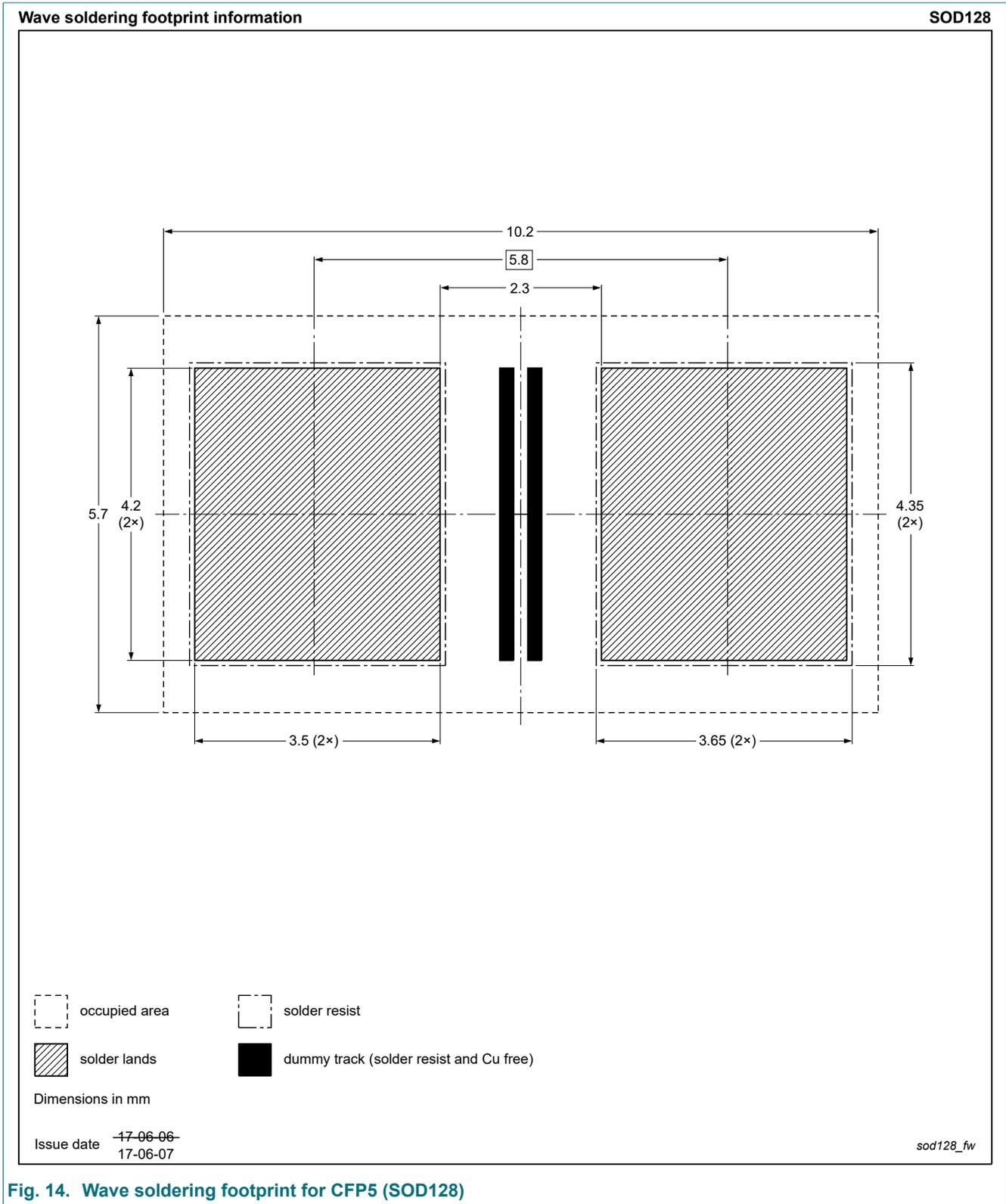


Fig. 14. Wave soldering footprint for CFP5 (SOD128)

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG6050ELP-Q v.1	20250310	Product data sheet	-	-

15. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. General description.....	1
2. Features and benefits.....	1
3. Applications.....	1
4. Quick reference data.....	1
5. Pinning information.....	1
6. Ordering information.....	2
7. Marking.....	2
8. Limiting values.....	2
9. Thermal characteristics.....	3
10. Characteristics.....	4
11. Test information.....	6
12. Package outline.....	7
13. Soldering.....	7
14. Revision history.....	9
15. Legal information.....	10

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